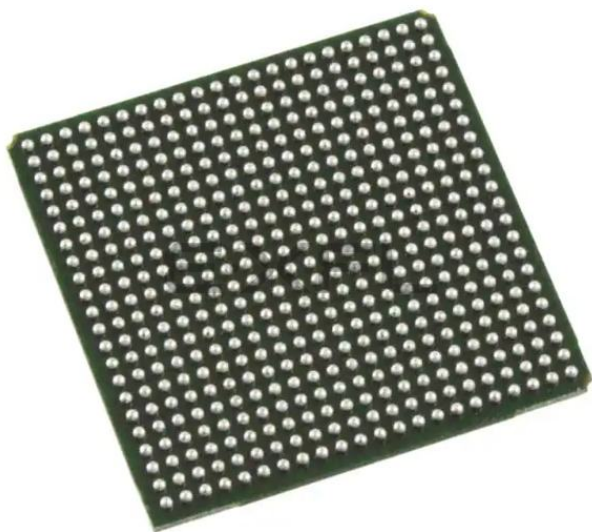




Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	4000
Number of Logic Elements/Cells	32000
Total RAM Bits	339968
Number of I/O	331
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-35e-5f484i

Architecture Overview

Each LatticeECP2/M device contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM™ Embedded Block RAM (EBR) and rows of sys-DSP™ Digital Signal Processing blocks, as shown in Figure 2-1. In addition, the LatticeECP2M family contains SERDES Quads in one or more of the corners. Figure 2-2 shows the block diagram of ECP2M20 with one quad.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and Programmable Functional Unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM and ROM functions. The PFF block contains building blocks for logic, arithmetic and ROM functions. Both PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and efficiently. Logic Blocks are arranged in a two-dimensional array. Only one type of block is used per row.

The LatticeECP2/M devices contain one or more rows of sysMEM EBR blocks. sysMEM EBRs are large dedicated 18K fast memory blocks. Each sysMEM block can be configured in a variety of depths and widths of RAM or ROM. In addition, LatticeECP2/M devices contain up to two rows of DSP Blocks. Each DSP block has multipliers and adder/accumulators, which are the building blocks for complex signal processing capabilities.

The LatticeECP2M devices feature up to 16 embedded 3.125Gbps SERDES (Serializer / Deserializer) channels. Each SERDES channel contains independent 8b/10b encoding / decoding, polarity adjust and elastic buffer logic. Each group of four SERDES channels along with its Physical Coding Sub-layer (PCS) block, creates a quad. The functionality of the SERDES/PCS Quads can be controlled by memory cells set during device configuration or by registers that are addressable during device operation. The registers in every quad can be programmed by a soft IP interface, referred to as the SERDES Client Interface (SCI). These quads (up to four) are located at the corners of the devices.

Each PIC block encompasses two PIOs (PIO pairs) with their respective sysI/O buffers. The sysI/O buffers of the LatticeECP2/M devices are arranged in eight banks, allowing the implementation of a wide variety of I/O standards. In addition, a separate I/O bank is provided for the programming interfaces. PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs. The PIC logic also includes pre-engineered support to aid in the implementation of high speed source synchronous standards such as SPI4.2, along with memory interfaces including DDR2.

The LatticeECP2/M registers in PFU and sysI/O can be configured to be SET or RESET. After power up and the device is configured, it enters into user mode with these registers SET/RESET according to the configuration setting, allowing the device entering to a known state for predictable system function.

Other blocks provided include PLLs, DLLs and configuration functions. The LatticeECP2/M architecture provides two General PLLs (GPLL) and up to six Standard PLLs (SPLL) per device. In addition, each LatticeECP2/M family member provides two DLLs per device. The GPLLs and DLLs blocks are located in pairs at the end of the bottom-most EBR row; the DLL block is located towards the edge of the device. The SPLL blocks are located at the end of the other EBR/DSP rows.

The configuration block that supports features such as configuration bit-stream decryption, transparent updates and dual boot support is located toward the center of this EBR row. The Ball Grid Array (BGA) package devices in the LatticeECP2/M family supports a sysCONFIG™ port located in the corner between banks four and five, which allows for serial or parallel device configuration.

In addition, every device in the family has a JTAG port. This family also provides an on-chip oscillator. The LatticeECP2/M devices use 1.2V as their core voltage.

MAC sysDSP Element

In this case, the two operands, A and B, are multiplied and the result is added with the previous accumulated value. This accumulated value is available at the output. The user can enable the input and pipeline registers, but the output register is always enabled. The output register is used to store the accumulated value. The Accumulators in the DSP blocks in the LatticeECP2/M family can be initialized dynamically. A registered overflow signal is also available. The overflow conditions are provided later in this document. Figure 2-24 shows the MAC sysDSP element.

Figure 2-24. MAC sysDSP

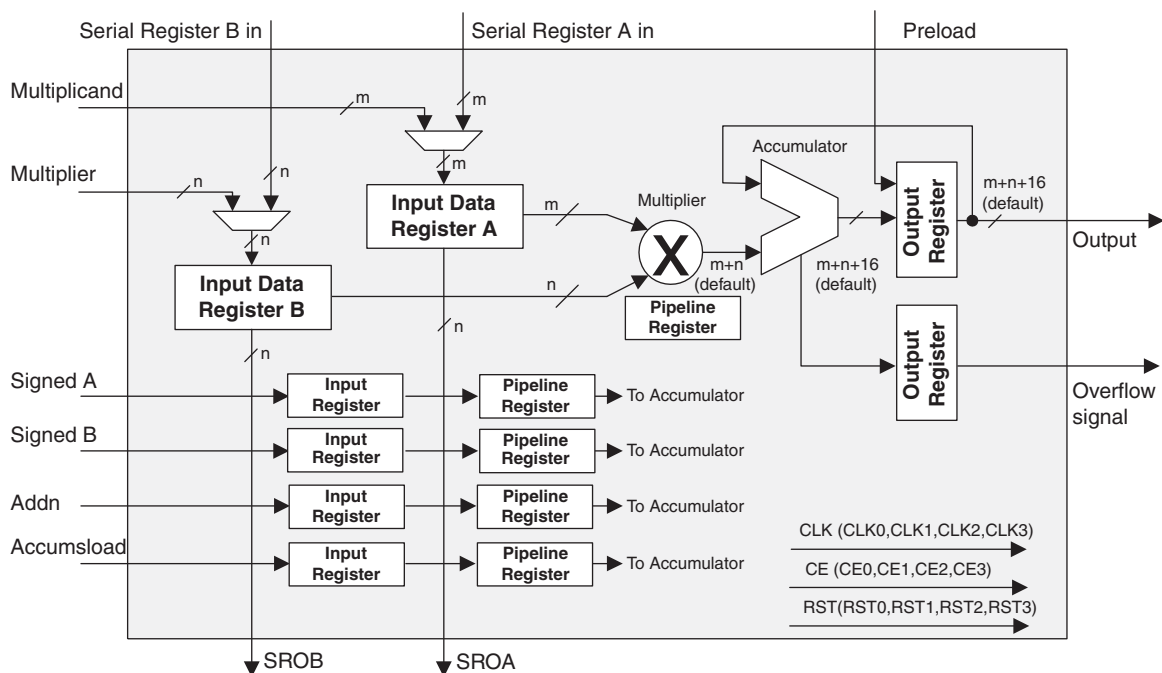
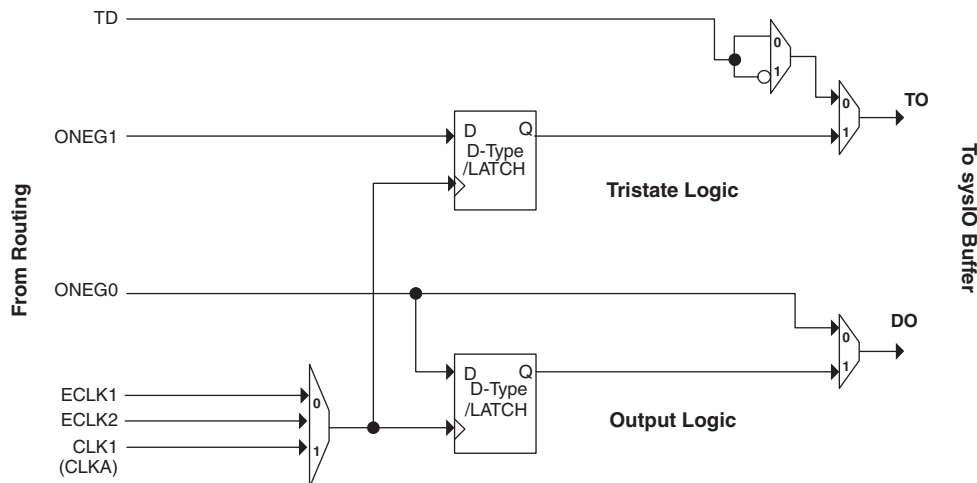


Figure 2-32. Output and Tristate Block, Top Edge



Note: Simplified version does not show CE and SET/RESET details.

Tristate Register Block

The tristate register block provides the ability to register tri-state control signals from the core of the device before they are passed to the sys/O buffers. The block contains a register for SDR operation and an additional latch for DDR operation. Figure 2-31 shows the diagram of the Tristate Register Block with the Output Block for the left, right and bottom edges and Figure 2-32 shows the diagram of the Tristate Register Block with the Output Block for the top edge.

In SDR mode, ONEG1 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG1 and OPOS1 are fed into registers on the positive edge of the clock. Then in the next clock the registered OPOS1 is latched. A multiplexer running off the same clock cycle selects the correct register for feeding to the output (DO).

Control Logic Block

The control logic block allows the selection and modification of control signals for use in the PIO block. A clock is selected from one of the clock signals provided from the general purpose routing, one of the edge clocks (ECLK1/ ECLK2) and a DQS signal provided from the programmable DQS pin and provided to the input register block. The clock can optionally be inverted.

DDR Memory Support

Certain PICs have additional circuitry to allow the implementation of high speed source synchronous and DDR memory interfaces. The support varies by the edge of the device as detailed below.

Left and Right Edges

PICs on these edges have registered elements that support DDR memory interfaces. One of every 16 PIOs contains a delay element to facilitate the generation of DQS signals. The DQS signal feeds the DQS bus that spans the set of 16 PIOs. Figure 2-33 shows the assignment of DQS pins in each set of 16 PIOs.

Bottom Edge

PICs on the bottom edge have registered elements that support DDR memory interfaces. One of every 18 PIOs contains a delay element to facilitate the generation of DQS signals. The DQS signal feeds the DQS bus that spans the set of 18 PIOs. Figure 2-34 shows the assignment of DQS pins in each set of 18 PIOs.

O standards (together with their supply and reference voltages) supported by LatticeECP2/M devices. For further information about utilizing the sysI/O buffer to support a variety of standards please see the the list of additional technical information at the end of this data sheet.

Table 2-13. Supported Input Standards

Input Standard	V _{REF} (Nom.)	V _{CCIO} ¹ (Nom.)
Single Ended Interfaces		
LVTTL	—	—
LVC MOS33	—	—
LVC MOS25	—	—
LVC MOS18	—	1.8
LVC MOS15	—	1.5
LVC MOS12	—	—
PCI 33	—	3.3
HSTL18 Class I, II	0.9	—
HSTL15 Class I	0.75	—
SSTL3 Class I, II	1.5	—
SSTL2 Class I, II	1.25	—
SSTL18 Class I, II	0.9	—
Differential Interfaces		
Differential SSTL18 Class I, II	—	—
Differential SSTL2 Class I, II	—	—
Differential SSTL3 Class I, II	—	—
Differential HSTL15 Class I	—	—
Differential HSTL18 Class I, II	—	—
LVDS, MLVDS, LVPECL, BLVDS, RSDS	—	—

¹ When not specified, V_{CCIO} can be set anywhere in the valid operating range (page 3-1).

Register-to-Register Performance (Continued)

Function	-7 Timing	Units
36x36 Multiplier (All Registers)	372	MHz
18x18 Multiplier/Accumulate (Input and Output Registers)	295	MHz
18x18 Multiplier-Add/Sub-Sum (All Reg- isters)	420	MHz
DSP IP Functions		
16-Tap Fully-Parallel FIR Filter	304	MHz
1024-pt, Radix 4, Decimation in Frequency FFT	227	MHz
8x8 Matrix Multiplier	223	MHz

Derating Timing Tables

Logic timing provided in the following sections of this data sheet and the Diamond design tool are worst case numbers in the operating range. Actual delays at nominal temperature and voltage for best case process, can be much better than the values given in the tables. The Diamond design tool can provide logic timing numbers at a particular temperature and voltage.

LatticeECP2/M Internal Switching Characteristics¹

Over Recommended Operating Conditions

Parameter	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
PFU/PFF Logic Mode Timing								
t _{LUT4_PFU}	LUT4 delay (A to D inputs to F output)	—	0.180	—	0.198	—	0.216	ns
t _{LUT6_PFU}	LUT6 delay (A to D inputs to OFX output)	—	0.304	—	0.331	—	0.358	ns
t _{LSR_PFU}	Set/Reset to output of PFU (Asynchronous)	—	0.600	—	0.655	—	0.711	ns
t _{SUM_PFU}	Clock to Mux (M0,M1) Input Setup Time	0.128	—	0.129	—	0.129	—	ns
t _{HM_PFU}	Clock to Mux (M0,M1) Input Hold Time	-0.051	—	-0.049	—	-0.046	—	ns
t _{SUD_PFU}	Clock to D input setup time	0.061	—	0.071	—	0.081	—	ns
t _{HD_PFU}	Clock to D input hold time	0.002	—	0.003	—	0.003	—	ns
t _{CK2Q_PFU}	Clock to Q delay, (D-type Register Configuration)	—	0.285	—	0.309	—	0.333	ns
PFU Dual Port Memory Mode Timing								
t _{CORAM_PFU}	Clock to Output (F Port)	—	0.902	—	1.083	—	1.263	ns
t _{SUDATA_PFU}	Data Setup Time	-0.172	—	-0.205	—	-0.238	—	ns
t _{HDATA_PFU}	Data Hold Time	0.199	—	0.235	—	0.271	—	ns
t _{SUADDR_PFU}	Address Setup Time	-0.245	—	-0.284	—	-0.323	—	ns
t _{HADDR_PFU}	Address Hold Time	0.246	—	0.285	—	0.324	—	ns
t _{SUWREN_PFU}	Write/Read Enable Setup Time	-0.122	—	-0.145	—	-0.168	—	ns
t _{HWREN_PFU}	Write/Read Enable Hold Time	0.132	—	0.156	—	0.180	—	ns
PIC Timing								
PIO Input/Output Buffer Timing								
t _{IN_PIO}	Input Buffer Delay (LVCMOS25)	—	0.613	—	0.681	—	0.749	ns
t _{OUT_PIO}	Output Buffer Delay (LVCMOS25)	—	1.115	—	1.115	—	1.343	ns
IOLOGIC Input/Output Timing								
t _{SUI_PIO}	Input Register Setup Time (Data Before Clock)	0.596	—	0.645	—	0.694	—	ns
t _{HI_PIO}	Input Register Hold Time (Data after Clock)	-0.570	—	-0.614	—	-0.658	—	ns
t _{COO_PIO}	Output Register Clock to Output Delay	—	0.61	—	0.66	—	0.72	ns
t _{SUCE_PIO}	Input Register Clock Enable Setup Time	0.032	—	0.037	—	0.041	—	ns
t _{HCE_PIO}	Input Register Clock Enable Hold Time	-0.022	—	-0.025	—	-0.028	—	ns
t _{SULSR_PIO}	Set/Reset Setup Time	0.184	—	0.201	—	0.217	—	ns
t _{HLSR_PIO}	Set/Reset Hold Time	-0.080	—	-0.086	—	-0.093	—	ns
EBR Timing								
t _{CO_EBR}	Clock (Read) to output from Address or Data	—	2.51	—	2.75	—	2.99	ns
t _{COO_EBR}	Clock (Write) to output from EBR output Register	—	0.33	—	0.36	—	0.39	ns
t _{SUDATA_EBR}	Setup Data to EBR Memory	-0.157	—	-0.181	—	-0.205	—	ns
t _{HDATA_EBR}	Hold Data to EBR Memory	0.173	—	0.195	—	0.217	—	ns
t _{SUADDR_EBR}	Setup Address to EBR Memory	-0.115	—	-0.130	—	-0.145	—	ns
t _{HADDR_EBR}	Hold Address to EBR Memory	0.138	—	0.155	—	0.172	—	ns
t _{SUWREN_EBR}	Setup Write/Read Enable to PFU Memory	-0.128	—	-0.149	—	-0.170	—	ns

sysCLOCK SPLL Timing

Over Recommended Operating Conditions

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
f _{IN}	Input Clock Frequency (CLKI, CLKFB)	Without external capacitor	33	—	420	MHz
		With external capacitor ^{5, 6}	2	—	420	MHz
f _{OUT}	Output Clock Frequency (CLKOP, CLKOS)	Without external capacitor	33	—	420	MHz
		With external capacitor ⁵	5	—	50	MHz
f _{OUT2}	K-Divider Output Frequency (CLKOK)	Without external capacitor	0.258	—	210	MHz
		With external capacitor ⁵	0.039	—	25	MHz
f _{VCO}	PLL VCO Frequency		640	—	1280	MHz
f _{PFD}	Phase Detector Input Frequency	Without external capacitor	33	—	420	MHz
		With external capacitor ⁶	2	—	50	MHz
AC Characteristics						
t _{DT}	Output Clock Duty Cycle	Default Duty Cycle Selected ³	45	50	55	%
t _{PH} ⁴	Output Phase Accuracy		—	—	±0.05	UI
t _{OPJIT} ¹	Output Clock Period Jitter	f _{OUT} ≥ 100 MHz	—	—	±125	ps
		50 ≤ f _{OUT} < 100 MHz	—	—	0.025	UIPP
		f _{OUT} < 50 MHz	—	—	0.04	UIPP
t _{SK}	Input Clock to Output Clock Skew	Divider Ratio = Integer	—	—	±250	ps
t _W	Output Clock Pulse Width	At 90% or 10%	1	—	—	ns
t _{LOCK} ²	PLL Lock-in Time	Without external capacitor	—	—	150	μs
		With external capacitor ⁵	—	—	500	μs
t _{IPJIT}	Input Clock Period Jitter		—	—	±200	ps
t _{FBKDLY}	External Feedback Delay		—	—	10	ns
t _{HI}	Input Clock High Time	90% to 90%	0.5	—	—	ns
t _{LO}	Input Clock Low Time	10% to 10%	0.5	—	—	ns
t _{RST}	RST Pulse Width (RSTK)		15	—	—	ns
	Reset Signal Pulse Width (RST)	Without external capacitor	500	—	—	ns
		With external capacitor ⁵	20	—	—	μs

1. Jitter sample is taken over 10,000 samples of the primary PLL output with clean reference clock and no additional I/O pins toggling.

2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.

3. Using LVDS output buffers.

4. Phase accuracy of CLKOS compared to CLKOP.

5. Value of external capacitor: 5.6 nF ±20%, NPO dielectric, ceramic chip capacitor, 1206 or smaller package, connected to PLLCAP pin.

6. $f_{OUT}(\max) = f_{IN} * 10$ for $f_{IN} < 5$ MHz.

LatticeECP2M Pin Information Summary, LFE2M50, LFE2M70 and LFE2M100 (Cont.)

Pin Type		LFE2M50			LFE2M70		LFE2M100	
		484 fpBGA	672 fpBGA	900 fpBGA	900 fpBGA	1152 fpBGA	900 fpBGA	1152 fpBGA
Available DDR-Interfaces per I/O Bank ¹	Bank0	0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0	0
	Bank2	2	2	2	4	4	4	4
	Bank3	2	1	1	3	4	3	5
	Bank4	3	1	3	3	3	3	3
	Bank5	2	3	3	2	3	2	3
	Bank6	1	2	2	3	4	3	5
	Bank7	3	3	3	4	4	4	5
	Bank8	0	0	0	0	0	0	0
PCI Capable I/Os per Bank	Bank0	0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0	0
	Bank2	0	0	0	0	72	0	80
	Bank3	0	0	0	0	64	0	80
	Bank4	50	24	48	48	40	48	44
	Bank5	60	60	50	40	40	40	46
	Bank6	52	54	60	62	66	62	82
	Bank7	60	60	68	70	74	70	90
	Bank8	0	0	0	0	0	0	0

1. Minimum requirement to implement a fully functional 8-bit wide DDR bus. Available DDR interface consists of at least 12 I/Os (1 DQS + 1 DQSB + 8 DQs + 1 DM + Bank VREF1).

Available Device Resources by Package, LatticeECP2

Resource	Device	256 fpBGA	484 fpBGA	672 fpBGA	900 fpBGA
PLL/DLL	ECP2-6	4	—	—	—
	ECP2-12	4	4	—	—
	ECP2-20	4	4	4	—
	ECP2-35	—	4	4	—
	ECP2-50	—	6	6	—
	ECP2-70	—	—	8	8

Available Device Resources by Package, LatticeECP2M

Resource	Device	256 fpBGA	484 fpBGA	672 fpBGA	900 fpBGA	1152 fpBGA
PLL/DLL	ECP2M20	10	10	—	—	—
	ECP2M35	10	10	10	—	—
	ECP2M50	—	10	10	10	—
	ECP2M70	—	—	—	10	10
	ECP2M100	—	—	—	10	10

LatticeECP2 Power Supply and NC (Cont.)

Signals	672 fpBGA ³	900 fpBGA ³
VCC	LFE2-20: R8, P18, M8, L20, L12, L13, L14, L15, M11, M12, M15, M16, N11, N16, P11, P16, R11, R12, R15, R16, T12, T13, T14, T15 LFE2-35/LFE2-50: L12, L13, L14, L15, M11, M12, M15, M16, N11, N16, P11, P16, R11, R12, R15, R16, T12, T13, T14, T15 LFE2-70: L12, L13, L14, L15, M11, M12, M15, M16, N11, N16, P11, P16, R11, R12, R15, R16, T12, T13, T14, T15	AA11, AA20, K11, K21, K22, L11, L12, L13, L18, L19, L20, M11, M20, N11, N20, V11, V20, W11, W20, Y10, Y11, Y12, Y13, Y18, Y19, Y20
VCCIO0	D11, D6, G9, J12, K12	J13, J14, K12, K13, K14, K15
VCCIO1	D16, D21, G18, J15, K15	J17, J18, J20, K17, K18, K20
VCCIO2	F23, J20, L23, M17, M18	L21, M21, M22, N21, N22, R21
VCCIO3	AA23, R17, R18, T23, V20	U21, U22, V21, V22, W21, Y22
VCCIO4	AC16, AC21, U15, V15, Y18	AA16, AA17, AA18, AA19, AB17, AB18
VCCIO5	AC11, AC6, U12, V12, Y9	AA12, AA13, AA14, AB12, AB13, AB14
VCCIO6	AA4, R10, R9, T4, V7	U10, U9, V10, W10, W9, Y9
VCCIO7	F4, J7, L4, M10, M9	L10, L9, M10, N10, P10, R10
VCCIO8	AE25, V18	AA21, Y21
VCCJ	AB5	AD3
VCCAUX	J10, J11, J16, J17, K18, L18, T18, U18, V16, V17, V10, V11, T9, U9, K9, L9	AA15, AB11, AB19, AB20, J11, J12, J19, K19, L22, M9, N9, P21, P9, T10, T21, V9, W22
VCCPLL	LFE2-20: None LFE2-35/LFE2-70: R8, P18 LFE2-50: R8, P18, M8, L20	P22, P8, T22, Y7
GND ¹	A2, A25, AA18, AA24, AA3, AA9, AD11, AD16, AD21, AD6, AE1, AE26, AF2, AF25, B1, B26, C11, C16, C21, C6, F18, F24, F3, F9, J13, J14, J21, J6, K10, K11, K13, K14, K16, K17, L10, L11, L16, L17, L24, L3, M13, M14, N10, N12, N13, N14, N15, N17, P10, P12, P13, P14, P15, P17, R13, R14, T10, T11, T16, T17, T24, T3, U10, U11, U13, U14, U16, U17, V13, V14, V21, V6	A1, A30, AC28, AC3, AH13, AH18, AH23, AH28, AH3, AH8, AK1, AK30, C13, C18, C23, C28, C3, C8, H28, H3, L14, L15, L16, L17, M12, M13, M14, M15, M16, M17, M18, M19, N12, N13, N14, N15, N16, N17, N18, N19, N28, N3, P11, P12, P13, P14, P15, P16, P17, P18, P19, P20, R11, R12, R13, R14, R15, R16, R17, R18, R19, R20, T11, T12, T13, T14, T15, T16, T17, T18, T19, T20, U11, U12, U13, U14, U15, U16, U17, U18, U19, U20, V12, V13, V14, V15, V16, V17, V18, V19, V28, V3, W12, W13, W14, W15, W16, W17, W18, W19, Y14, Y15, Y16, Y17
NC ²	LFE2-20: E4, E3, E2, E1, H6, H5, F2, F1, H8, J9, G4, G3, K3, K2, K1, L2, L1, M2, M1, N2, T1, T2, P8, P6, P5, P4, U1, V1, P3, R3, R4, U2, V2, W2, T6, R5, AA19, W17, Y19, Y17, AF20, AE20, AA20, W18, AD20, AE21, AF21, AF22, R22, T21, P26, P25, R24, R23, P20, R19, P21, P19, P23, P22, N22, R21, N26, N25, J26, J25, J23, K23, H26, H25, H24, H23, F22, E24, D25, C25, D24, B25, H21, G22, B24, C24, D23, C23, E19, C19, B21, B20, D19, B19, G17, E18, G19, F17, A20, A19, E17, D18, M3, N6, P24 LFE2-35: K3, K2, K1, L2, L1, M2, M1, N2, M8, P3, R3, R4, U2, V2, W2, AF20, AE20, AA20, W18, AD20, AE21, AF21, AF22, P26, P25, R24, R23, P20, R19, L20, J26, J25, J23, K23, H26, H25, H24, H23, E19, C19, B21, B20, D19, B19, G17, E18, G19, F17, A20, A19, E17, D18, M3, N6, P24 LFE2-50: N6, P24, M3 LFE2-70: M8, L20, M3, P24, N6	A2, A3, A4, A5, AB28, AC4, AD23, AE1, AE2, AE29, AE3, AE30, AE4, AE5, AE6, AF1, AF2, AF23, AF26, AF27, AF28, AF29, AF3, AF30, AF4, AF5, AG1, AG13, AG16, AG18, AG2, AG26, AG27, AG28, AG29, AG3, AG30, AG4, AG8, AH1, AH16, AH2, AH26, AH27, AH29, AH30, AH4, AJ1, AJ2, AJ27, AJ28, AJ29, AJ3, AJ30, AK2, AK27, AK28, AK29, AK3, B1, B2, B3, B30, B4, B5, C1, C2, C29, C30, C4, D13, D18, D23, D28, D29, D3, D30, D4, E25, E26, E27, E28, E29, E3, E30, E4, E5, E6, F25, F5, F6, G6, G7, K10, K9, N27, N4, R1, R2, V27, V4

1. All grounds must be electrically connected at the board level. For fpBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.

2. NC pins should not be connected to any active signals, VCC or GND.

3. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 208 PQFP

LFE2-12E/SE					LFE2-20E/SE				
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential	
1	PL2A	7	VREF2_7	T (LVDS)*	PL2A	7	VREF2_7	T (LVDS)*	
2	PL2B	7	VREF1_7	C (LVDS)*	PL2B	7	VREF1_7	C (LVDS)*	
3	PL4A	7		T (LVDS)*	PL6A	7	LDQ8	T (LVDS)*	
4	PL4B	7		C (LVDS)*	PL6B	7	LDQ8	C (LVDS)*	
5	GND	-			GND	-			
6	PL6A	7	LDQ10	T (LVDS)*	PL12A	7	LDQ16	T (LVDS)*	
7	VCCAUX	-			VCCAUX	-			
8	PL6B	7	LDQ10	C (LVDS)*	PL12B	7	LDQ16	C (LVDS)*	
9	PL8A	7	LDQ10	T (LVDS)*	PL14A	7	LDQ16	T (LVDS)*	
10	VCCIO7	7			VCCIO7	7			
11	PL8B	7	LDQ10	C (LVDS)*	PL14B	7	LDQ16	C (LVDS)*	
12	VCC	-			VCC	-			
13	GND	-			GND	-			
14	VCCIO7	7			VCCIO7	7			
15	PL12A	7	LDQ10	T (LVDS)*	PL18A	7	LDQ16	T (LVDS)*	
16	PL12B	7	LDQ10	C (LVDS)*	PL18B	7	LDQ16	C (LVDS)*	
17	GND	-			GND	-			
18	PL13A	7	PCLKT7_0/LDQ10	T	PL19A	7	PCLKT7_0/LDQ16	T	
19	VCC	-			VCC	-			
20	PL13B	7	PCLKC7_0/LDQ10	C	PL19B	7	PCLKC7_0/LDQ16	C	
21	PL15A	6	PCLKT6_0	T (LVDS)*	PL21A	6	PCLKT6_0/LDQ25	T (LVDS)*	
22	PL15B	6	PCLKC6_0	C (LVDS)*	PL21B	6	PCLKC6_0/LDQ25	C (LVDS)*	
23	PL16A	6	VREF2_6	T	PL22A	6	VREF2_6/LDQ25	T	
24	PL16B	6	VREF1_6	C	PL22B	6	VREF1_6/LDQ25	C	
25	GND	-			GND	-			
26	PL17A	6	LLM0_GDLLT_IN_A**	T (LVDS)*	PL27A	6	LLM0_GDLLT_IN_A**/LDQ25	T (LVDS)*	
27	PL17B	6	LLM0_GDLLC_IN_A**	C (LVDS)*	PL27B	6	LLM0_GDLLC_IN_A**/LDQ25	C (LVDS)*	
28	VCC	-			VCC	-			
29	LLM0_PLLCAP	6			LLM0_PLLCAP	6			
30	VCCAUX	-			VCCAUX	-			
31	PL20A	6	LLM0_GPLLT_IN_A**	T (LVDS)*	PL30A	6	LLM0_GPLLT_IN_A**/LDQ34	T (LVDS)*	
32	GND	-			GND	-			
33	PL21A	6	LLM0_GPLLT_FB_A	T	PL31A	6	LLM0_GPLLT_FB_A/LDQ34	T	
34	PL20B	6	LLM0_GPLLC_IN_A**	C (LVDS)*	PL30B	6	LLM0_GPLLC_IN_A**/LDQ34	C (LVDS)*	
35	PL21B	6	LLM0_GPLLC_FB_A	C	PL31B	6	LLM0_GPLLC_FB_A/LDQ34	C	
36	PL23A	6			PL33A	6	LDQ34		
37	PL24A	6	LDQ28	T (LVDS)*	PL38A	6	LDQ42	T (LVDS)*	
38	VCCIO6	6			VCCIO6	6			
39	PL24B	6	LDQ28	C (LVDS)*	PL38B	6	LDQ42	C (LVDS)*	
40	VCC	-			VCC	-			
41	PL26A	6	LDQ28	T (LVDS)*	PL40A	6	LDQ42	T (LVDS)*	
42	GND	-			GND	-			
43	PL26B	6	LDQ28	C (LVDS)*	PL40B	6	LDQ42	C (LVDS)*	
44	VCCIO6	6			VCCIO6	6			
45	PL28A	6	LDQS28	T (LVDS)*	PL42A	6	LDQS42	T (LVDS)*	

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-35E/SE					LFE2-50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
K1	PL23B	7	LDQ22	C	PL42B	7	LDQ41	C	
L4	PL24A	7	LDQ22	T (LVDS)*	PL43A	7	LDQ41	T (LVDS)*	
L3	PL24B	7	LDQ22	C (LVDS)*	PL43B	7	LDQ41	C (LVDS)*	
L2	PL25A	7	PCLKT7_0/LDQ22	T	PL44A	7	PCLKT7_0/LDQ41	T	
GNDIO	GNDIO7	-			GNDIO7	-			
L1	PL25B	7	PCLKC7_0/LDQ22	C	PL44B	7	PCLKC7_0/LDQ41	C	
M5	PL27A	6	PCLKT6_0/LDQ31	T (LVDS)*	PL46A	6	PCLKT6_0/LDQ50	T (LVDS)*	
M6	PL27B	6	PCLKC6_0/LDQ31	C (LVDS)*	PL46B	6	PCLKC6_0/LDQ50	C (LVDS)*	
M3	PL28A	6	VREF2_6/LDQ31	T	PL47A	6	VREF2_6/LDQ50	T	
M4	PL28B	6	VREF1_6/LDQ31	C	PL47B	6	VREF1_6/LDQ50	C	
M2	PL29A	6	LDQ31	T (LVDS)*	PL48A	6	LDQ50	T (LVDS)*	
VCCIO	VCCIO6	6			VCCIO	6			
M1	PL29B	6	LDQ31	C (LVDS)*	PL48B	6	LDQ50	C (LVDS)*	
N1	PL30A	6	LDQ31	T	PL49A	6	LDQ50	T	
N2	PL30B	6	LDQ31	C	PL49B	6	LDQ50	C	
GNDIO	GNDIO6	-			GNDIO6	-			
VCCIO	VCCIO6	6			VCCIO	6			
N3	PL39A	6	LDQS39***	T (LVDS)*	PL58A	6	LDQS58***	T (LVDS)*	
N4	PL39B	6	LDQ39	C (LVDS)*	PL58B	6	LDQ58	C (LVDS)*	
N5	PL40A	6	LDQ39	T	PL59A	6	LDQ58	T	
VCCIO	VCCIO6	6			VCCIO	6			
P5	PL40B	6	LDQ39	C	PL59B	6	LDQ58	C	
P1	PL41A	6	LLM0_GDLLT_IN_A**/LDQ39	T (LVDS)*	PL60A	6	LLM0_GDLLT_IN_A**/LDQ58	T (LVDS)*	
P2	PL41B	6	LLM0_GDLLC_IN_A**/LDQ39	C (LVDS)*	PL60B	6	LLM0_GDLLC_IN_A**/LDQ58	C (LVDS)*	
P4	PL42A	6	LLM0_GDLLT_FB_A/LDQ39	T	PL61A	6	LLM0_GDLLT_FB_A/LDQ58	T	
GNDIO	GNDIO6	-			GNDIO6	-			
R4	PL42B	6	LLM0_GDLLC_FB_A/LDQ39	C	PL61B	6	LLM0_GDLLC_FB_D/LDQ58	C	
P6	LLM0_PLLCAP	6			LLM0_PLLCAP	6			
R1	PL44A	6	LLM0_GPLLT_IN_A**/LDQ48	T (LVDS)*	PL63A	6	LLM0_GPLLT_IN_A**/LDQ67	T (LVDS)*	
R2	PL44B	6	LLM0_GPLLC_IN_A**/LDQ48	C (LVDS)*	PL63B	6	LLM0_GPLLC_IN_A**/LDQ67	C (LVDS)*	
R3	PL45A	6	LLM0_GPLLT_FB_A/LDQ48	T	PL64A	6	LLM0_GPLLT_FB_A/LDQ67	T	
T4	PL45B	6	LLM0_GPLLC_FB_A/LDQ48	C	PL64B	6	LLM0_GPLLC_FB_A/LDQ67	C	
T1	PL46A	6	LDQ48	T (LVDS)*	PL65A	6	LDQ67	T (LVDS)*	
VCCIO	VCCIO6	6			VCCIO	6			
T2	PL46B	6	LDQ48	C (LVDS)*	PL65B	6	LDQ67	C (LVDS)*	
T5	PL47A	6	LDQ48	T	PL66A	6	LDQ67	T	
T3	PL47B	6	LDQ48	C	PL66B	6	LDQ67	C	
GNDIO	GNDIO6	-			VCCIO	6			
VCCIO	VCCIO6	-			GNDIO6	-			
U1	PL52A	6	LDQ56	T (LVDS)*	PL71A	6	LDQ75	T (LVDS)*	
U2	PL52B	6	LDQ56	C (LVDS)*	PL71B	6	LDQ75	C (LVDS)*	
V1	PL53A	6	LDQ56	T	PL72A	6	LDQ75	T	
V2	PL53B	6	LDQ56	C	PL72B	6	LDQ75	C	
VCCIO	VCCIO6	6			VCCIO	6			
R6	PL54A	6	LDQ56	T (LVDS)*	PL73A	6	LDQ75	T (LVDS)*	
T6	PL54B	6	LDQ56	C (LVDS)*	PL73B	6	LDQ75	C (LVDS)*	

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
U10	VCCIO6	6		
U9	VCCIO6	6		
V10	VCCIO6	6		
W10	VCCIO6	6		
W9	VCCIO6	6		
Y9	VCCIO6	6		
L10	VCCIO7	7		
L9	VCCIO7	7		
M10	VCCIO7	7		
N10	VCCIO7	7		
P10	VCCIO7	7		
R10	VCCIO7	7		
AA21	VCCIO8	8		
Y21	VCCIO8	8		
AA15	VCCAUX	-		
AB11	VCCAUX	-		
AB19	VCCAUX	-		
AB20	VCCAUX	-		
J11	VCCAUX	-		
J12	VCCAUX	-		
J19	VCCAUX	-		
K19	VCCAUX	-		
L22	VCCAUX	-		
M9	VCCAUX	-		
N9	VCCAUX	-		
P21	VCCAUX	-		
P9	VCCAUX	-		
T10	VCCAUX	-		
T21	VCCAUX	-		
V9	VCCAUX	-		
W22	VCCAUX	-		
A1	GND	-		
A30	GND	-		
AC28	GND	-		
AC3	GND	-		
AH13	GND	-		
AH18	GND	-		
AH23	GND	-		
AH28	GND	-		
AH3	GND	-		
AH8	GND	-		
AK1	GND	-		
AK30	GND	-		

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
F15	NC	-			NC	-		
F14	NC	-			NC	-		
F13	NC	-			NC	-		
G12	NC	-			NC	-		
G13	NC	-			NC	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

***For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated sysCONFIG pins for the higher density devices (ECP2M50, ECP2M70 and ECP2M100).

****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
AH12	VCC	-			LLC_SQ_VCCR1	14			
AK8	PB16A	5	BDQ15	T	LLC_SQ_HDOUTP1	14		T	
AH8	NC	-			LLC_SQ_VCCOB1	14			
AJ8	PB16B	5	BDQ15	C	LLC_SQ_HDOUTN1	14		C	
AH9	VCC	-			LLC_SQ_VCCTX1	14			
AJ9	PB17B	5	BDQ15	C	LLC_SQ_HDOUTN0	14		C	
AK10	NC	-			LLC_SQ_VCCOB0	14			
AK9	PB17A	5	BDQ15	T	LLC_SQ_HDOUTP0	14		T	
AH10	VCC	-			LLC_SQ_VCCTX0	14			
AJ12	PB19B	5	BDQ15	C	LLC_SQ_HDINN0	14		C	
AJ13	NC	-			LLC_SQ_VCCIB0	14			
AK12	PB19A	5	BDQ15	T	LLC_SQ_HDINP0	14		T	
AH13	VCC	-			LLC_SQ_VCCR0	14			
AF10	PB3A	5	BDQ6	T	PB30A	5	BDQ33	T	
AE8	PB3B	5	BDQ6	C	PB30B	5	BDQ33	C	
AE11	PB4A	5	BDQ6	T	PB31A	5	BDQ33	T	
VCCIO	VCCIO5	5			VCCIO5	5			
AD9	PB4B	5	BDQ6	C	PB31B	5	BDQ33	C	
AE10	PB5A	5	BDQ6	T	PB32A	5	BDQ33	T	
AD10	PB5B	5	BDQ6	C	PB32B	5	BDQ33	C	
AE13	PB6A	5	BDQS6	T	PB33A	5	BDQS33	T	
GNDIO	GNDIO5	-			GNDIO5	-			
AC12	PB6B	5	BDQ6	C	PB33B	5	BDQ33	C	
AG2	PB7A	5	BDQ6	T	PB34A	5	BDQ33	T	
AG3	PB7B	5	BDQ6	C	PB34B	5	BDQ33	C	
AD13	PB8A	5	BDQ6	T	PB35A	5	BDQ33	T	
VCCIO	VCCIO5	5			VCCIO5	5			
AC13	PB8B	5	BDQ6	C	PB35B	5	BDQ33	C	
AE14	PB9A	5	BDQ6	T	PB36A	5	BDQ33	T	
AC14	PB9B	5	BDQ6	C	PB36B	5	BDQ33	C	
AF3	PB10A	5	BDQ6	T	PB37A	5	BDQ33	T	
GNDIO	GNDIO5	-			GNDIO5	-			
AF4	PB10B	5	BDQ6	C	PB37B	5	BDQ33	C	
VCCIO	VCCIO5	5			-	-			
AG4	PB20A	5	BDQ24	T	PB38A	5	BDQ42	T	
AG5	PB20B	5	BDQ24	C	PB38B	5	BDQ42	C	
GNDIO	GNDIO5	-			-	-			
VCCIO	VCCIO5	5			-	-			
AD11	PB24A	5	BDQS24****	T	PB39A	5	BDQ42	T	
AF13	PB24B	5	BDQ24	C	PB39B	5	BDQ42	C	
AF12	PB25A	5	BDQ24	T	PB40A	5	BDQ42	T	
-	-	-			VCCIO5	5			
AD14	PB25B	5	BDQ24	C	PB40B	5	BDQ42	C	
AG8	PB26A	5	BDQ24	T	PB41A	5	BDQ42	T	
AF8	PB26B	5	BDQ24	C	PB41B	5	BDQ42	C	
AE15	PB27A	5	BDQ24	T	PB42A	5	BDQS42****	T	
-	-	-			GNDIO5	-			
VCCIO	VCCIO5	5			-	-			

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
M26	PR27A	2	RDQS27	T (LVDS)*	PR37A	2	RDQS37	T (LVDS)*	
L30	PR26B	2	RDQ27	C	PR36B	2	RDQ37	C	
GNDIO	GNDIO2	-			GNDIO2	-			
L29	PR26A	2	RDQ27	T	PR36A	2	RDQ37	T	
L28	PR25B	2	RDQ27	C (LVDS)*	PR35B	2	RDQ37	C (LVDS)*	
L27	PR25A	2	RDQ27	T (LVDS)*	PR35A	2	RDQ37	T (LVDS)*	
H29	PR24B	2	RDQ27	C	PR34B	2	RDQ37	C	
VCCIO	VCCIO2	2			VCCIO2	2			
G29	PR24A	2	RDQ27	T	PR34A	2	RDQ37	T	
L22	PR23B	2	RDQ27	C (LVDS)*	PR33B	2	RDQ37	C (LVDS)*	
M22	PR23A	2	RDQ27	T (LVDS)*	PR33A	2	RDQ37	T (LVDS)*	
F30	PR21B	2		C	PR31B	2	RDQ28	C	
GNDIO	GNDIO2	-			GNDIO2	-			
F29	PR21A	2		T	PR31A	2	RDQ28	T	
-	-	-			-	-			
-	-	-			-	-			
E30	PR20B	2		C (LVDS)*	PR30B	2	RDQ28	C (LVDS)*	
E29	PR20A	2		T (LVDS)*	PR30A	2	RDQ28	T (LVDS)*	
VCCIO	VCCIO2	2			-	-			
L25	PR19B	2		C	PR29B	2	RDQ28	C	
L26	PR19A	2		T	PR29A	2	RDQ28	T	
-	-	-			VCCIO2	2			
H28	PR18B	2		C (LVDS)*	PR28B	2	RDQ28	C (LVDS)*	
J28	PR18A	2		T (LVDS)*	PR28A	2	RDQS28	T (LVDS)*	
G28	PR16B	2		C	PR27B	2	RDQ28	C	
GNDIO	GNDIO2	-			GNDIO2	-			
G27	PR16A	2		T	PR27A	2	RDQ28	T	
L24	NC	-			PR26B	2	RDQ28	C (LVDS)*	
L23	NC	-			PR26A	2	RDQ28	T (LVDS)*	
D30	NC	-			PR25B	2	RDQ28	C	
-	-	-			VCCIO2	2			
D29	NC	-			PR25A	2	RDQ28	T	
K24	NC	-			PR24B	2	RDQ28	C (LVDS)*	
K25	NC	-			PR24A	2	RDQ28	T (LVDS)*	
J27	NC	-			PR22B	2		C	
-	-	-			GNDIO2	-			
K26	NC	-			PR22A	2		T	
K23	PR15B	2		C (LVDS)*	PR21B	2		C (LVDS)*	
K22	PR15A	2		T (LVDS)*	PR21A	2		T (LVDS)*	
J22	PR14B	2		C	PR20B	2		C	
VCCIO	VCCIO2	-			VCCIO2	2			
J23	PR14A	2		T	PR20A	2		T	
-	-	-			GNDIO2	-			
-	-	-			-	-			
J26	NC	-			PR17B	2	RDQ15	C (LVDS)*	
H26	NC	-			PR17A	2	RDQ15	T (LVDS)*	
H27	NC	-			PR16B	2	RDQ15	C	
G26	NC	-			PR16A	2	RDQ15	T	

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
C29	URC_SQ_VCCR1	12		
B28	URC_SQ_HDINN1	12		C
C28	URC_SQ_VCCIB1	12		
A28	URC_SQ_HDINP1	12		T
B24	URC_SQ_VCCAUX33	12		
E24	URC_SQ_REFCLKN	12		C
D24	URC_SQ_REFCLKP	12		T
C24	URC_SQ_VCCP	12		
A20	URC_SQ_HDINP2	12		T
C20	URC_SQ_VCCIB2	12		
B20	URC_SQ_HDINN2	12		C
C19	URC_SQ_VCCR2	12		
A23	URC_SQ_HDOUTP2	12		T
C23	URC_SQ_VCCOB2	12		
B23	URC_SQ_HDOUTN2	12		C
C22	URC_SQ_VCCTX2	12		
B22	URC_SQ_HDOUTN3	12		C
A21	URC_SQ_VCCOB3	12		
A22	URC_SQ_HDOUTP3	12		T
C21	URC_SQ_VCCTX3	12		
B19	URC_SQ_HDINN3	12		C
B18	URC_SQ_VCCIB3	12		
A19	URC_SQ_HDINP3	12		T
C18	URC_SQ_VCCR3	12		
D23	PT100B	1		C
GNDIO	GNDIO1	-		
E21	PT100A	1		T
D26	PT99B	1		C
E26	PT99A	1		T
E23	PT98B	1		C
VCCIO	VCCIO1	1		
G22	PT98A	1		T
-	-	-		
D22	PT97B	1		C
F21	PT97A	1		T
G18	PT96B	1		C
H18	PT96A	1		T
D20	PT95B	1		C
GNDIO	GNDIO1	-		
D21	PT95A	1		T
E20	PT94B	1		C
VCCIO	VCCIO1	1		
E19	PT94A	1		T

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
D19	PT93B	1		C
E18	PT93A	1		T
D18	PT92B	1		C
C17	PT92A	1		T
A17	PT91B	1		C
B17	PT91A	1		T
GNDIO	GNDIO1	-		
VCCIO	VCCIO1	1		
J18	PT75B	1		C
J19	PT75A	1		T
H17	PT74B	1		C
J17	PT74A	1		T
F18	PT73B	1		C
F17	PT73A	1		T
GNDIO	GNDIO1	-		
A16	PT72B	1		C
B16	PT72A	1		T
G17	PT71B	1		C
G16	PT71A	1		T
VCCIO	VCCIO1	1		
H16	PT70B	1		C
F16	PT70A	1		T
J16	PT69B	1		C
G15	PT69A	1		T
GNDIO	GNDIO1	-		
C16	PT68B	1		C
D16	PT68A	1		T
J15	PT67B	1		C
H15	PT67A	1		T
VCCIO	VCCIO1	1		
A15	PT66B	1	VREF2_1	C
B15	PT66A	1	VREF1_1	T
F15	PT65B	1	PCLKC1_0	C
E16	PT65A	1	PCLKT1_0	T
C15	PT64B	0	PCLKC0_0	C
GNDIO	GNDIO0	-		
D15	PT64A	0	PCLKT0_0	T
C14	PT63B	0	VREF2_0	C
E15	PT63A	0	VREF1_0	T
G14	PT62B	0		C
VCCIO	VCCIO0	0		
J14	PT62A	0		T
F14	PT61B	0		C

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
K11	NC	-			NC	-		
K12	NC	-			NC	-		
K13	NC	-			NC	-		
K23	NC	-			NC	-		
K24	NC	-			NC	-		
K25	NC	-			NC	-		
K26	NC	-			NC	-		
L11	NC	-			NC	-		
L12	NC	-			NC	-		
L13	NC	-			NC	-		
L14	NC	-			NC	-		
L21	NC	-			NC	-		
L22	NC	-			NC	-		
L23	NC	-			NC	-		
L24	NC	-			NC	-		
L25	NC	-			NC	-		
L26	NC	-			NC	-		
M11	NC	-			NC	-		
M24	NC	-			NC	-		
M25	NC	-			NC	-		
M6	NC	-			NC	-		
M8	NC	-			NC	-		
N10	NC	-			NC	-		
N11	NC	-			NC	-		
P10	NC	-			NC	-		
P25	NC	-			NC	-		
P26	NC	-			NC	-		
R9	NC	-			NC	-		
T11	NC	-			NC	-		
U11	NC	-			NC	-		
W11	NC	-			NC	-		
Y10	NC	-			NC	-		
Y11	NC	-			NC	-		
R15	VCCPLL	-			VCCPLL	-		
R20	VCCPLL	-			VCCPLL	-		
Y15	VCCPLL	-			VCCPLL	-		
Y20	VCCPLL	-			VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

*** For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated pins for the higher density devices (ECP2M50, ECP2M70, and ECP2M100).

****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-20E-5Q208I	131	1.2V	-5	PQFP	208	IND	20
LFE2-20E-6Q208I	131	1.2V	-6	PQFP	208	IND	20
LFE2-20E-5F256I	193	1.2V	-5	fpBGA	256	IND	20
LFE2-20E-6F256I	193	1.2V	-6	fpBGA	256	IND	20
LFE2-20E-5F484I	331	1.2V	-5	fpBGA	484	IND	20
LFE2-20E-6F484I	331	1.2V	-6	fpBGA	484	IND	20
LFE2-20E-5F672I	402	1.2V	-5	fpBGA	672	IND	20
LFE2-20E-6F672I	402	1.2V	-6	fpBGA	672	IND	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-35E-5F484I	331	1.2V	-5	fpBGA	484	IND	35
LFE2-35E-6F484I	331	1.2V	-6	fpBGA	484	IND	35
LFE2-35E-5F672I	450	1.2V	-5	fpBGA	672	IND	35
LFE2-35E-6F672I	450	1.2V	-6	fpBGA	672	IND	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-50E-5F484I	339	1.2V	-5	fpBGA	484	IND	50
LFE2-50E-6F484I	339	1.2V	-6	fpBGA	484	IND	50
LFE2-50E-5F672I	500	1.2V	-5	fpBGA	672	IND	50
LFE2-50E-6F672I	500	1.2V	-6	fpBGA	672	IND	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-70E-5F672I	500	1.2V	-5	fpBGA	672	IND	70
LFE2-70E-6F672I	500	1.2V	-6	fpBGA	672	IND	70
LFE2-70E-5F900I	583	1.2V	-5	fpBGA	900	IND	70
LFE2-70E-6F900I	583	1.2V	-6	fpBGA	900	IND	70